

LIST OF REFERENCES CITED BY APPLICANT <i>(Use several sheets if necessary)</i>	ATTY. DOCKET NO. 664.01-US	SERIAL NO. 09/543628
	APPLICANT Honeywell International Inc.	
	FILING DATE April 5, 2000	GROUP Not Yet Assigned



U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
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	JJ							
	KK							
	LL							
	MM							
	NN							

OTHER REFERENCES *(Including Author, Title, Date, Pertinent Pages, Etc.)*

MF	OO	Iwamoto, N. E. "Applying Polymer Process Studies Using Molecular Modeling". Proceedings of the 4 th International Conference on Adhesive Joining and Coating Technology in Electronics Manufacturing (Adhesives in Microelectronics 2000) June 18-21, Helsinki, Finland; pp. 182-187.
MF	PP	Iwamoto, N.E. "Advancing Polymer Process Understanding in Package and Board Applications...". Proceedings of the 50 th Electronic Components and Technology Conference; May 21-24, 2000; Las Vegas, NV. Pp. 1354-1359
MF	QQ	Iwamoto, N.E. "Simulating Stress Reliability Using Molecular Modeling Methodologies". 32 nd International Symposium on Microelectronics; Chicago, Ill; October 26-28, 1999, Proceedings pp. 415-420.

EXAMINER <i>Michael J. [Signature]</i>	DATE CONSIDERED 6/19/01
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.